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BEIJING ZHONGXUN SIFANG SCIENCE & TECHNOLOGY CO.,LTD.

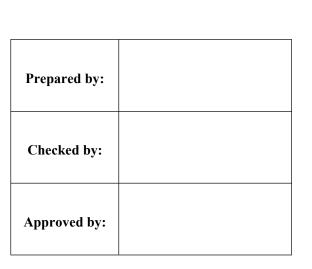
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Part No.	:	SF6115
Pages	:	6
Date	:	2013/09/10
Revision	:	1.0



SF6115

6.5MHz Bandwidth

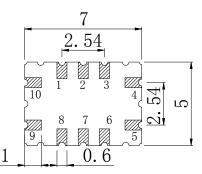
Application

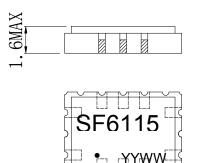
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 6.5 MHz

Features

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 7.00x5.00x1.60mm³
- Package Code QCC12C
- Electrostatic Sensitive Device(ESD)

Package Dimensions (Unit: mm)





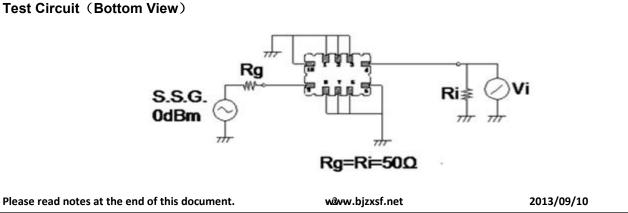
Pin Configuration

Pin No.	Description
9	Input
4	Output
1,2,3,6,7,8,	Case Ground
5,10	To be Grounded

Marking Description

0.5	SF	Trademark	
SF	F	SAW Filter	
6115	Part Number		
•	Pin 1		
YYWW	Year Code & \	Week Code	

*Fig: If the products produced in 06th week of 2015, The year code & week code is 1506.



Performance

Maximum Rating

ltem		Value	Unit
DC Voltage	V _{DC}	3	V
Operation Temperature	т	-40 ~ +85	°C
Storage Temperature	T _{stg}	-55 ~ +125	°C
RF Power Dissipation	Р	15	dBm

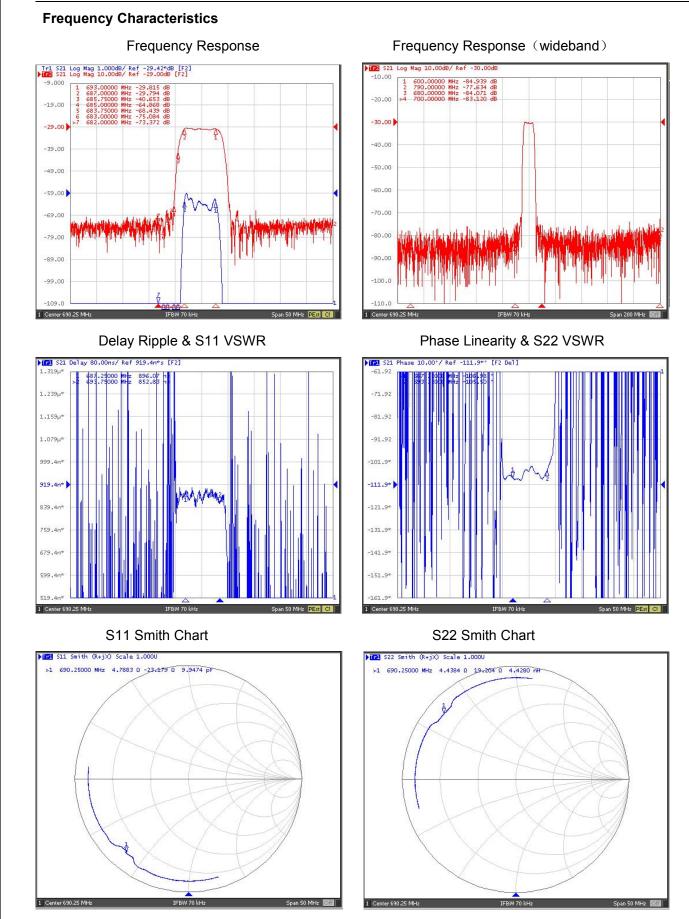
Electronic Characteristics

Test Temperature: 25℃±2℃

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		690.25		MHz
Insertion Loss(min)	IL		30.0	34.0	dB
Amplitude Ripple (p-p) 687.25 - 693.75MHz	Δα		1.0	3.0	dB
Group Delay Ripple 687.25 - 693.75MHz	GDR		100.0	300.0	ns
Absolute Attenuation	α				
600.00 - 682.00MHz			40.0		dB
685.00MHz		30.0	35.0		dB
683.00MHz		37.0	40.0		dB
700.00-790.00MHz			40.0		dB



Please read notes at the end of this document.

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2013/09/10

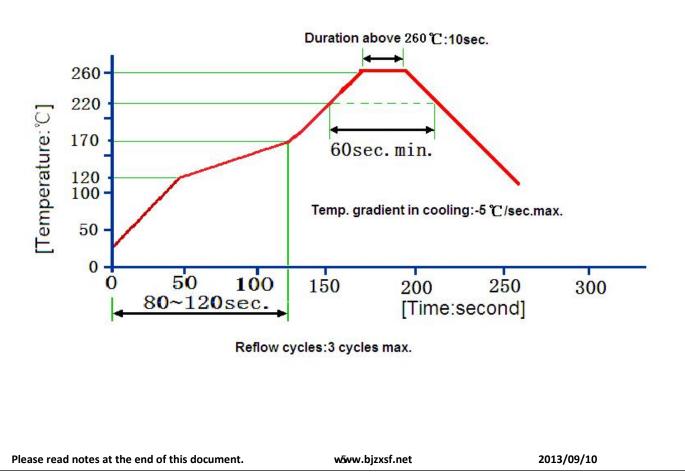
SF6115

6.5MHz Bandwidth

No.	Test item	Test condition
1 Temperature		(1) Temperature: $85^\circ C \pm 2^\circ C$, Duration: 250h , Recovery time: 2h±0.5h
	Storage	(2) Temperature: –55℃±3℃, Duration: 250h, Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60 ℃ ±2 ℃ , 90~95% RH Duration: 250h
0	The second Ohersel	Heat cycle conditions: TA=-55℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch
3 Thermal Shock		time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	4 Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm
4		Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
		Temperature: 245°C±5°C Duration: 3.0s5.0s
6 Solder Ability Test		Depth: DIP2/3 , SMD1/5
		(1)Thickness of PCB:1mm , Solder condition: 260 $^\circ\!\mathrm{C}\pm5^\circ\!\mathrm{C}$, Duration: 10±1s
7	Resistance to Soldering Heat	(2)Temperature of Soldering Iron: 350 $^\circ\!\!\mathbb{C}\pm10^\circ\!\!\mathbb{C}$, Duration: 3~4s ,
		Recovery time $\cdot 2 \pm 0.5h$

Reliability (The SAW components shall remain electrical performance after tests)

Recommended Reflow Soldering Diagram



Notes

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.